

IIT MADRAS Technology Transfer Office TTO - IPM Cell



Industrial Consultancy & Sponsored Research (IC&SR)

## A Method for Producing High Performance Cryorolled Ultrafine **Grained Bimetallic Composite Sheets** ITM Technology Available for Licensing

PROBLEMSTATEMENT

Indian Institute of Technology Madras

- Bimetals, particularly AI/Cu bimetals, are widely used in various industries due their hybrid properties. They are to particularly popular in electrical cables components like and connectors.
- Traditional manufacturing methods like  $\triangleright$ bonding, diffusion roll bonding, explosive welding, and ultrasonic welding are suitable for AI/Cu bimetallic joining. However, intermetallic formation in these processes can reduce electrical conductivity and properties.
- ≻ Roll bonding is the most popular technique for producing Al/Cu bimetallic sheets due to its ease of use and process flexibility.
- ≻ A technologically new, advanced manufacturing route is needed to achieve superior interface, ultra-high excellent bond strength, and mechanical properties.

## TECHNOLOGYCATEGORY MARKET

Technology: Crvorolled Ultrafine Grained **Bimetallic Composite Sheets** Category: Advanced materials Industry: Electronic System & Design

Manufacturing (ESDM)

Application: Electrical and Electronics Industries.

Market: The global market size of projected to grow from USD 6.67 billion in 2018 to USD 12.17 billion by 2027, at a CAGR of 6.92%.

## INIELLECIUAL PROPERTY

IITM IDF Ref. 2492 Patent No: IN 528430

TRL (Technology Readiness Level)

**TRL-4**, Experimentally validated in Lab;

## **CONTACT US**

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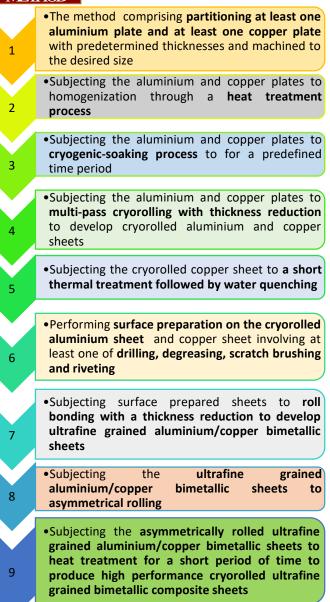
IITM TTO Website: https://ipm.icsr.in/ipm/

## **Research Lab**

Prof. Sushanta Kumar Panigrahi, Dept. of Mechanical Engineering.

## TECHNOLOGY

### MEIHOD



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# Indian Institute of Technology Madras



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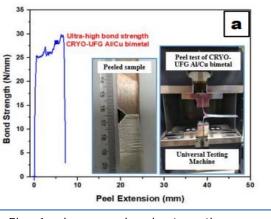


Fig 1 shows a bond strength vs peel CRYO-UFG Al/Cu extension, plots of bimetallic composite sheets

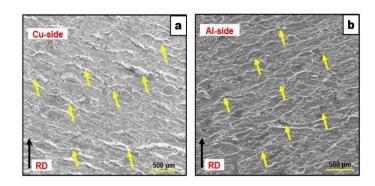


Fig 2 shows a Scanning Electron Microscope (SEM) magnification fractography of peel tested CRYO-UFG AI/Cu

## Key Features / Value Proposition

#### Temperature

✓ Cryorolling is performed at a very low of approximately minus (-) 196°C.

#### Soaking

✓ The aluminium and copper plates in liquid nitrogen for minimum 15 mins before each pass.

#### A 2-High rolling mill

✓ Approximately 125 roll mm diameters and the rolling is carried out at approximately 6 to 8 rpm.

#### Thickness reduction

✓ 80% during multi-pass cryorolling with an average grain size of approximately 1 µm

#### Short thermal treatment

b Cu

✓ 250°C to 450°C for a time period of 5 to 15 minutes.

#### Roll bonding

- ✓ a thickness reduction range of approximately 55 to 60%.
- □ Roll Spec
  - ✓ Roller diameter 300 mm
  - ✓ Rolling speed 4-6 rpm and
  - ✓ Rolling load 30-45 tons

#### □ Speed ratio

- ✓ Approximately 1.1 to 1.5 on a 2-high rolling.
- Bond strength
  - ✓ Approximately 24 to 28 N/mm and
- Excellent **strength-ductility** synergy
  - ✓ (tensile) strength of approximately 200MPa and
- □ Total ductility of ( 35 to 40%) approximately.





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